

September 2014

ES3A - ES3J Fast Rectifiers

Features

- For Surface Mount Applications
- · Glass-Passivated Junction
- · Low-Profile Package
- · Easy Pick and Place
- · Built-in Strain Relief
- · Superfast Recovery Times for High Efficiency



Ordering Information

| Part Number | Top Mark | Package | Packing Method |
|-------------|----------|----------------|----------------|
| ES3A | ES3A | DO-214AB (SMC) | Tape and Reel |
| ES3B | ES3B | DO-214AB (SMC) | Tape and Reel |
| ES3C | ES3C | DO-214AB (SMC) | Tape and Reel |
| ES3D | ES3D | DO-214AB (SMC) | Tape and Reel |
| ES3J | ES3J | DO-214AB (SMC) | Tape and Reel |

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at $T_A = 25^{\circ}\text{C}$ unless otherwise noted.

| Symbol | Parameter | | Value | | | | |
|----------------------------------|--|--|-------------|------|------|------|------|
| | | | ES3B | ES3C | ES3D | ES3J | Unit |
| V _{RRM} | Maximum Repetitive Reverse Voltage | | 100 | 150 | 200 | 600 | V |
| I _{F(AV)} | Average Rectified Forward Current, .375" Lead Length at T _A = 75°C 3.0 | | | Α | | | |
| I _{FSM} | Non-Repetitive Peak Forward Surge Current 8.3 ms Single Half-Sine Wave | | Α | | | | |
| T _{J,} T _{STG} | Operating Junction and Storage Temperature Range | | -50 to +150 | | | | |

Thermal Characteristics

Values are at $T_A = 25$ °C unless otherwise noted.

| Symbol | | Value | Unit | | |
|-----------------|---|------------------------------------|------|------|--|
| P _D | Power Dissipation | | 1.66 | W | |
| D | Thermal Resistance, Junction to Ambient ⁽¹⁾ | Maximum Land Pattern: 16 x 16 mm | 47 | °C/W | |
| $R_{\theta JA}$ | | Minimum Land Pattern: 2.6 x 3.2 mm | 125 | C/VV | |
| | Thermal Resistance, Junction to Lead ⁽¹⁾ | Maximum Land Pattern: 16 x 16 mm | 12 | °C/W | |
| | | Minimum Land Pattern: 2.6 x 3.2 mm | 16 | C/VV | |

Note:

1. Device mounted on FR-4 PCB 0.013 mm.

Electrical Characteristics

Values are at $T_A = 25$ °C unless otherwise noted.

| Symbol | Parameter | Conditions | | Value | | | | Unit | |
|----------------------|-------------------------|---|------|-------|------|------|------|------|-------|
| Syllibol | i arameter | | | ES3A | ES3B | ES3C | ES3D | ES3J | Oilit |
| V_{F} | Maximum Forward Voltage | I _F = 3.0 A | | 0.95 | | | 1.70 | V | |
| t _{rr} Reve | | $I_F = 0.5 A,$ | Тур. | | 2 | :0 | | 35 | |
| | Reverse Recovery Time | $I_R = 1.0 \text{ A},$ $I_{RR} = 0.25 \text{ A}$ | Max. | | 3 | 0 | | 45 | ns |
| I_ | Maximum Reverse Current | T _A = 25°C | | 10 | | | | μА | |
| I _R | at Rated V _R | $T_A = 100^{\circ}C$ 500 | | | μΑ | | | | |
| C _T | Total Capacitance | V _R = 4.0 V, f = 1.0 MHz | | | | 45 | | | pF |

Typical Performance Characteristics

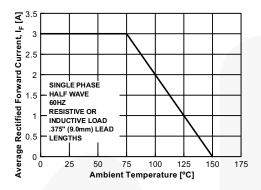


Figure 1. Forward Current Derating Curve

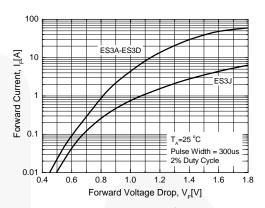


Figure 2. Foward Voltage Characteristics

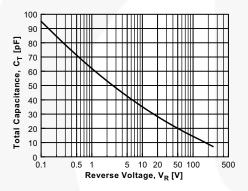


Figure 3. Total Capacitance

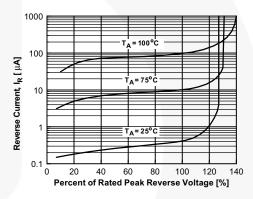
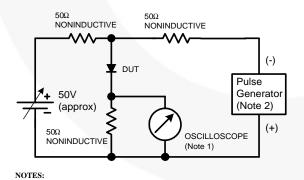


Figure 4. Reverse Current vs. Reverse Voltage



1. Rise time = 7.0 ns max; Input impedance = 1.0 megaohm 22 pf. 2. Rise time = 10 ns max; Source impedance = 50 ohms.

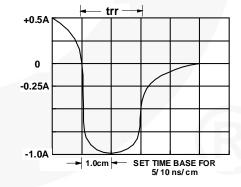


Figure 5. Reverse Recovery Time Characteristic and Test Circuit Diagram

Physical Dimension

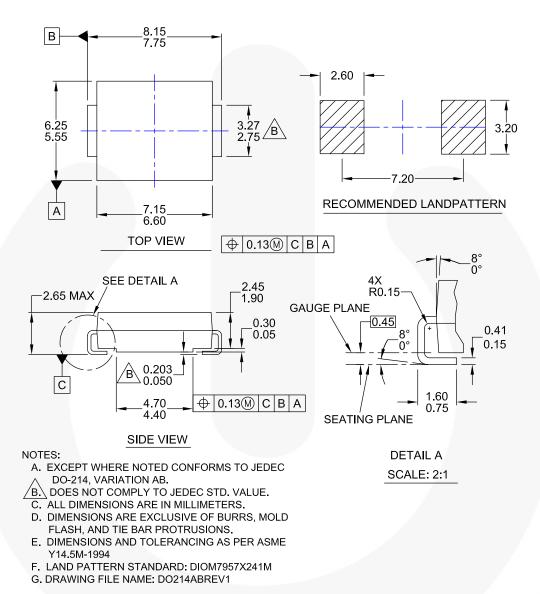


Figure 6. 2-LEAD, SMC, JEDEC DO-214, VARIATION AB (ACTIVE)





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| Definition of Terms | | | | | | |
|--------------------------|-----------------------|---|--|--|--|--|
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